WHAT IS CLAIMED IS:

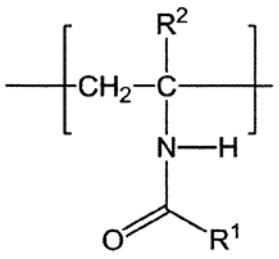
1. A surface treatment composition for removing organic residues present on a surface of a polishing object after polishing, comprising:

a polymer having a constituent unit represented by Formula (1) below;

an ionic dispersant which is a high molecular weight compound having a sulfonic acid group, and

water,

the surface treatment composition being used for treating a surface of a polishing object after polishing,



(1)

wherein, in Formula (1) above, R^1 is a hydrocarbon group having 1 to 5 carbon atoms and R^2 is a hydrogen atom or a hydrocarbon group having 1 to 3 carbon atoms,

wherein, the surface treatment composition has a pH of 3 or less.

2. The surface treatment composition according to Claim 1, wherein

the surface treatment composition is substantially free from an abrasive.

3. The surface treatment composition according to Claim 1 or 2, wherein

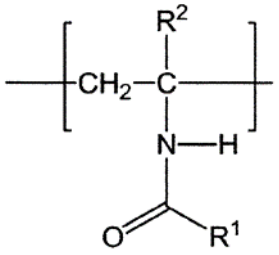
the polishing object after polishing contains polysilicon.

4. The surface treatment composition according to any one of Claims 1 to 3, wherein

a weight average molecular weight of the polymer is 50,000 or more and 900,000 or less.

5. A method for producing a surface treatment composition for removing organic residues present on a surface of a polishing object after polishing, comprising:

mixing a polymer having a constituent unit represented by Formula (1) below, an ionic dispersant which is a high molecular weight compound having a sulfonic acid group, and water,



(1)

wherein, in Formula (1) above, R^1 is a hydrocarbon group having 1 to 5 carbon atoms and R^2 is a hydrogen atom or a hydrocarbon group having 1 to 3 carbon atoms

wherein, the surface treatment composition has a pH of 3 or less.

6. A surface treatment method comprising:

surface-treating a polishing object after polishing using the surface treatment composition according to any one of Claims 1 to 4 to reduce an organic residue on a surface of the polishing object after polishing.

7. The surface treatment method according to Claim 6, wherein

the surface treatment includes rinse polishing or cleaning.

8. A method for producing a semiconductor substrate comprising:

a surface treatment step of reducing an organic residue on a surface of a polishing object after polishing by the surface treatment method according to Claim 6 or 7, wherein

the polishing object after polishing is a semiconductor substrate after polishing.